

8th CIES Technology Forum **VIRTUAL**

March 27 (Mon) – 28 (Tue), 2023

International Symposium

March 28 (Tue) **DAY2**

http://www.cies.tohoku.ac.jp/8th_forum/

Part 1 [Live] 9:00-12:10 (JST)

| JST | PDT | CET | | |
|-------------|-------------------------|-----------|---|---|
| 9:00-9:05 | March 27 17:00-17:05 | 1:00-1:05 | Opening remarks | Tetsuo Endoh (Tohoku Univ.) |
| 9:05-9:35 | 17:05-17:35 | 1:05-1:35 | Invited talk 1 Status and Outlook of eMRAM Technology | Tae Young Lee (Samsung Electronics) |
| 9:35-10:05 | 17:35-18:05 | 1:35-2:05 | Invited talk 2 Material Development toward Low Power SOT-MRAM | Chi-Feng Pai (TSMC) |
| 10:05-10:35 | 18:05-18:35 | 2:05-2:35 | Invited talk 3 First Demonstration of Full Integration and Characterization of 4F ² 1S1M Cells with 45 nm of Pitch and 20 nm of MTJ Size | Sooman Seo (SK Hynix) |
| 10:35-11:05 | 18:35-19:05 | 2:35-3:05 | Invited talk 4 iPMA-type Hexa-MTJ for High Density eFlash-type MRAM | Hiroaki Honjo (Tohoku Univ.) |
| 11:05-11:35 | 19:05-19:35 | 3:05-3:35 | Invited talk 5 GaN IC Roadmaps | Alex Lidow (Efficient Power Conversion) |
| 11:35-12:05 | 19:35-20:05 | 3:35-4:05 | Invited talk 6 Progress in Power Electronics Integration Technology | Yoshikazu Takahashi (Tohoku Univ.) |
| 12:05-12:10 | 20:05-20:10 | 4:05-4:10 | Closing remarks | Tetsuo Endoh (Tohoku Univ.) |

Part 2 [Streaming] 17:00-20:10 (JST)

| JST | PDT | CET | | |
|-------------|-----------|-------------|---|---|
| 17:00-17:05 | 1:00-1:05 | 9:00-9:05 | Opening remarks | Tetsuo Endoh (Tohoku Univ.) |
| 17:05-17:35 | 1:05-1:35 | 9:05-9:35 | Invited talk 1 Status and Outlook of eMRAM Technology | Tae Young Lee (Samsung Electronics) |
| 17:35-18:05 | 1:35-2:05 | 9:35-10:05 | Invited talk 2 Material Development toward Low Power SOT-MRAM | Chi-Feng Pai (TSMC) |
| 18:05-18:35 | 2:05-2:35 | 10:05-10:35 | Invited talk 3 First Demonstration of Full Integration and Characterization of 4F ² 1S1M Cells with 45 nm of Pitch and 20 nm of MTJ Size | Sooman Seo (SK Hynix) |
| 18:35-19:05 | 2:35-3:05 | 10:35-11:05 | Invited talk 4 iPMA-type Hexa-MTJ for High Density eFlash-type MRAM | Hiroaki Honjo (Tohoku Univ.) |
| 19:05-19:35 | 3:05-3:35 | 11:05-11:35 | Invited talk 5 GaN IC Roadmaps | Alex Lidow (Efficient Power Conversion) |
| 19:35-20:05 | 3:35-4:05 | 11:35-12:05 | Invited talk 6 Progress in Power Electronics Integration Technology | Yoshikazu Takahashi (Tohoku Univ.) |
| 20:05-20:10 | 4:05-4:10 | 12:05-12:10 | Closing remarks | Tetsuo Endoh (Tohoku Univ.) |

Organizer: Center for Innovative Integrated Electronic Systems (CIES), Tohoku Univ.

Co-sponsored: Research Institute of Electrical Communication (RIEC), Tohoku Univ.

Sponsors: CAO, MEXT, METI, JPO, JSPS, JST, NEDO, INPIT